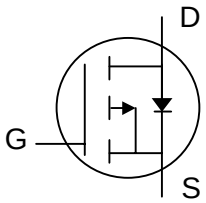
P-channel Enhancement-mode Power MOSFET

Lower On-resistance

Simple Drive Requirement

Fast Switching Characteristic

RoHS-compliant, halogen-free



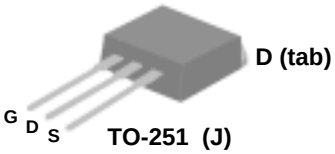
BV_{DSS}	-60V
$R_{DS(ON)}$	100mΩ
I_D	-14A

Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, low on-resistance and cost-effectiveness.

The AP9576GH-HF-3 is in the TO-252 package, which is widely used for commercial and industrial surface-mount applications, and is well suited for low voltage applications such as DC/DC converters.
The AP9576GJ-HF-3 is in the TO-251 through-hole package which is used where a small PCB footprint or an attached heatsink is required.

TO-252 (H)



TO-251 (J)

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-60	V
V_{GS}	Gate-Source Voltage	±20	V
I_D at T_A=25°C	Continuous Drain Current[3]	-14	A
I_D at T_A=100°C	Continuous Drain Current[3]	-9	A
I_{DM}	Pulsed Drain Current[1]	-45	A
P_D at T_A=25°C	Total Power Dissipation	36.8	W
	Linear Derating Factor	0.29	W/°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Value	Unit
Rthj-c	Maximum Thermal Resistance, Junction-case	3.4	°C/W
Rthj-a	Maximum Thermal Resistance, Junction-ambient (PCB Mount)[3]	62.5	°C/W
Rthj-a	Maximum Thermal Resistance, Junction-ambient	110	°C/W

Ordering Information

AP9576GH-HF-3TR : in RoHS-compliant halogen-free TO-252, shipped on tape and reel (3000 pcs/reel)

AP9576GJ-HF-3TB : in RoHS-compliant halogen-free TO-251, shipped in tubes (80pcs/tube)

Electrical Specifications at T_j=25°C (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=-250uA	-60	-	-	V
$\Delta BV_{DSS}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to 25°C, I_D=-1mA	-	-0.06	-	V/°C
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}= -10V, I_D=-10A	-	-	100	mΩ
		V_{GS}= -4.5V, I_D=-8A	-	-	120	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=-250uA	-0.8	-	-3	V
g_{fs}	Forward Transconductance	V_{DS}=-10V, I_D=-5A	-	6	-	S
I_{DSS}	Drain-Source Leakage Current	V_{DS}=-60V, V_{GS}=0V	-	-	-10	uA
	Drain-Source Leakage Current (T_j=125°C)	V_{DS}=-48V, V_{GS}=0V	-	-	-250	uA
I_{GSS}	Gate-Source Leakage	V_{GS}=±20V, V_{DS}=0V	-	-	±100	nA
Q_g	Total Gate Charge[2]	I_D=--10A	-	14	22	nC
Q_{gs}	Gate-Source Charge	V_{DS}=-48V	-	3	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	V_{GS}=-4.5V	-	6	-	nC
$t_{d(on)}$	Turn-on Delay Time[2]	V_{DS}=-30V	-	8	-	ns
t_r	Rise Time	I_D=-10A	-	18	-	ns
$t_{d(off)}$	Turn-off Delay Time	R_G=3.3Ω , V_{GS}=-10V	-	32	-	ns
t_f	Fall Time	R_D= 3Ω	-	56	-	ns
C_{iss}	Input Capacitance	V_{GS}=0V	-	1170	1880	pF
C_{oss}	Output Capacitance	V_{DS}=-25V	-	120	-	pF
C_{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	90	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage[2]	I_S= -10A, V_{GS}=0V	-	-	-1.2	V
t_{rr}	Reverse Recovery Time[2]	I_S=-10A, V_{GS}=0V	-	39	-	ns
Q_{rr}	Reverse Recovery Charge	dI/dt=-100A/µs	-	59	-	nC

Notes:

1.Pulse width limited by safe operating area

2.Pulse test - pulse width ≤ 300µs, duty cycle ≤ 2%

3.Surface mounted on 1 in copper pad of FR4 board

Typical Electrical Characteristics

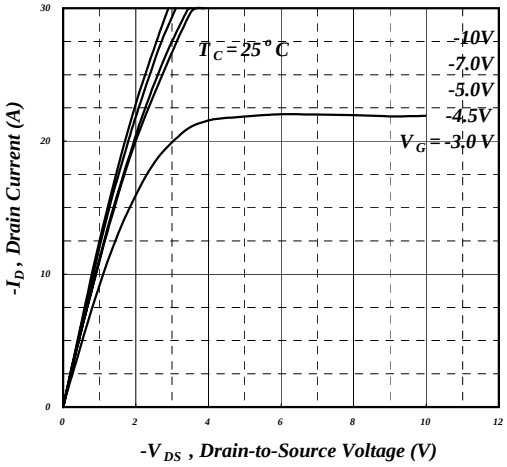


Fig 1. Typical Output Characteristics

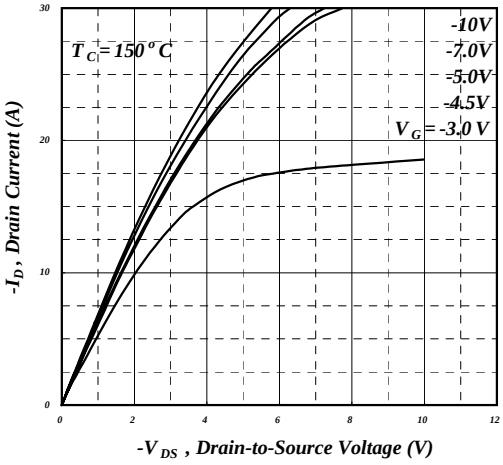


Fig 2. Typical Output Characteristics

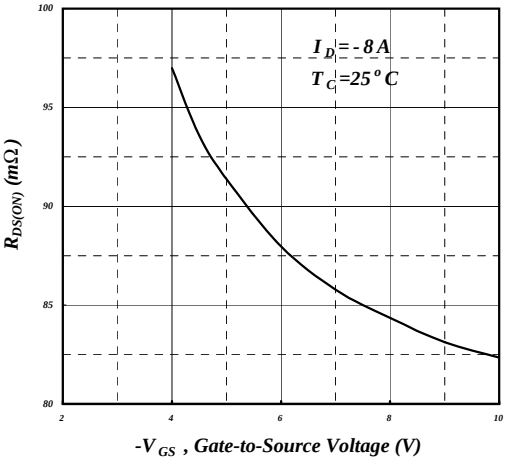


Fig 3. On-Resistance vs. Gate Voltage

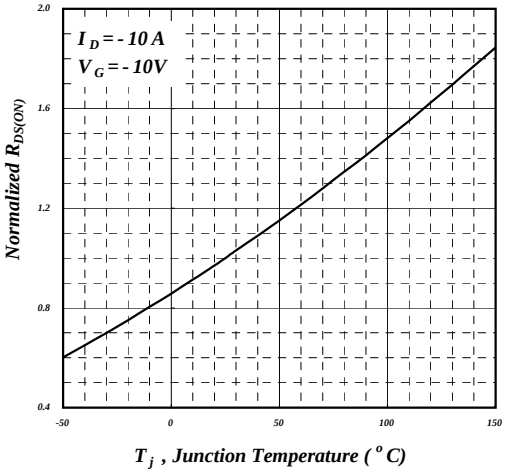


Fig 4. Normalized On-Resistance vs. Junction Temperature

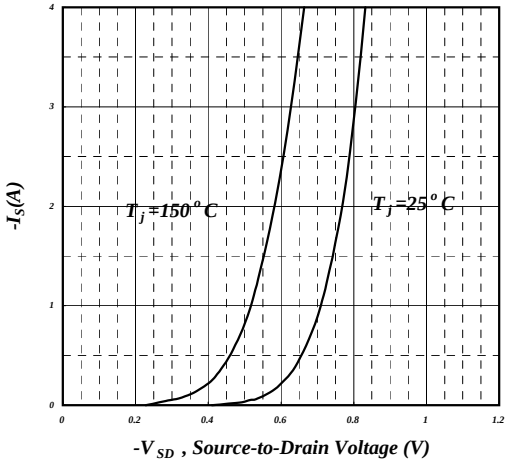


Fig 5. Forward Characteristic of Reverse Diode

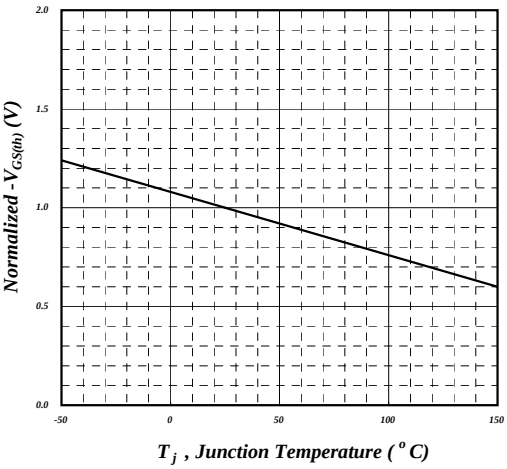


Fig 6. Gate Threshold Voltage vs. Junction Temperature

Typical Electrical Characteristics (cont.)

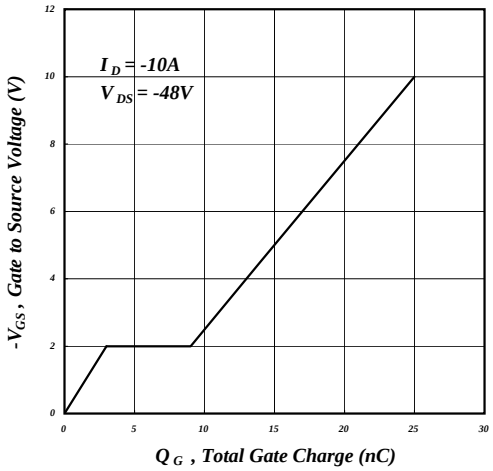


Fig 7. Gate Charge Characteristics

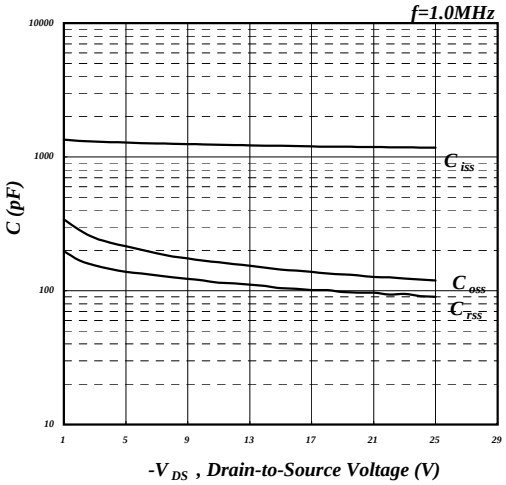


Fig 8. Typical Capacitance Characteristics

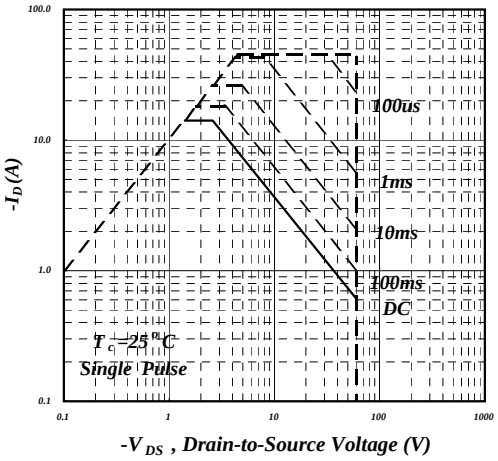


Fig 9. Maximum Safe Operating Area

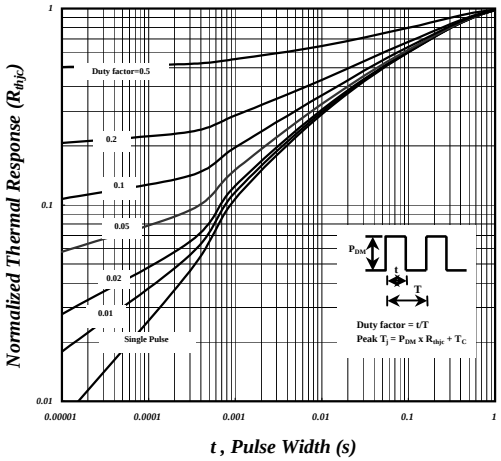


Fig 10. Effective Transient Thermal Impedance

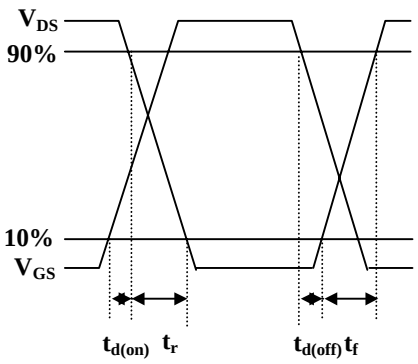


Fig 11. Switching Time Waveforms

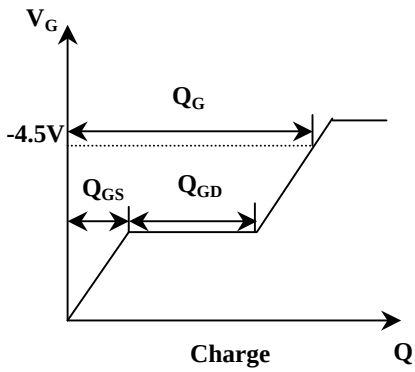
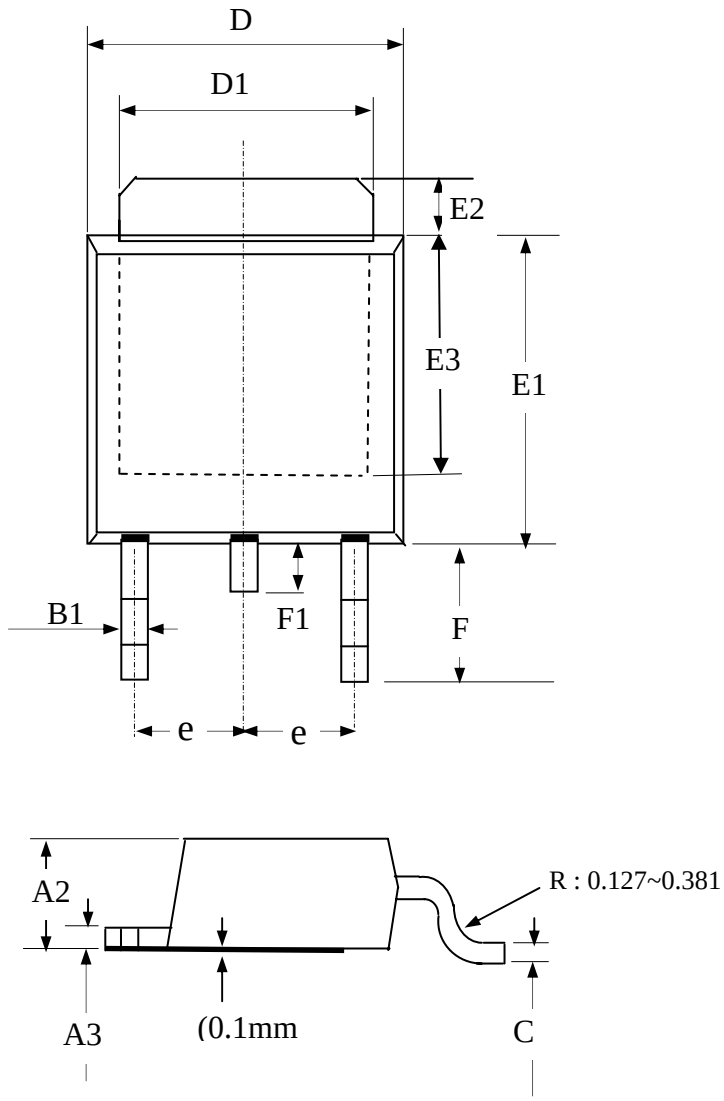


Fig 12. Gate Charge Waveform

Package Dimensions: TO-252

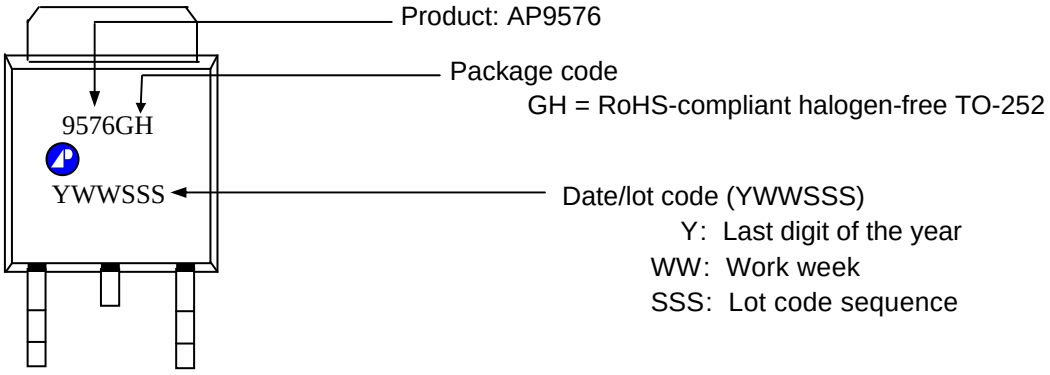


SYMBOLS	Millimeters		
	MIN	NOM	MAX
A2	1.80	2.30	2.80
A3	0.40	0.50	0.60
B1	0.40	0.70	1.00
D	6.00	6.50	7.00
D1	4.80	5.35	5.90
E3	3.50	4.00	4.50
F	2.20	2.63	3.05
F1	0.50	0.85	1.20
E1	5.10	5.70	6.30
E2	0.50	1.10	1.80
e	--	2.30	--
C	0.35	0.50	0.65

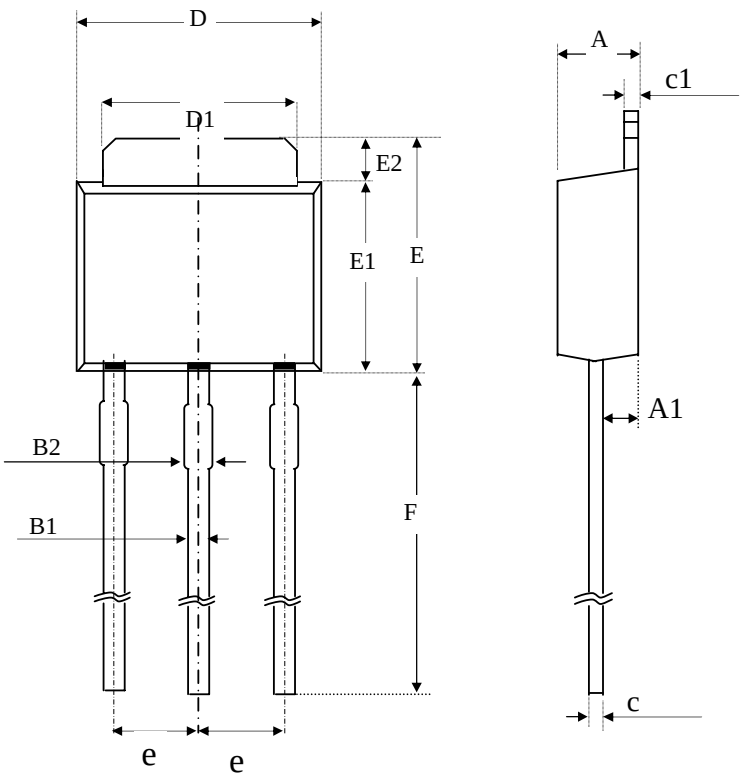
1. All dimensions are in millimeters.
2. Dimensions do not include mold protrusions.

Marking Information

Laser Marking



Package Dimensions: TO-251



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A	2.20	2.30	2.40
A1	0.90	1.20	1.50
B1	0.40	0.60	0.80
B2	0.60	0.85	1.05
c	0.40	0.50	0.60
c1	0.40	0.50	0.60
D	6.40	6.60	6.80
D1	4.80	5.20	5.50
E	6.70	7.00	7.30
E1	5.40	5.60	5.80
E2	1.30	1.50	1.70
e	----	2.30	----
F	7.00	8.30	9.60

1. All dimensions are in millimeters.
2. Dimensions do not include mold protrusions.

Marking Information